

**NTS074N03P3H**

N-channel 30V Enhancement Mode Power MOSFET



**VOLTAGE:** 30 Volts

**CURRENT:** 50 Amperes

PDFN3\*3

Marking and Polarity

**FEATURES**

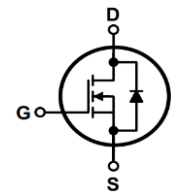
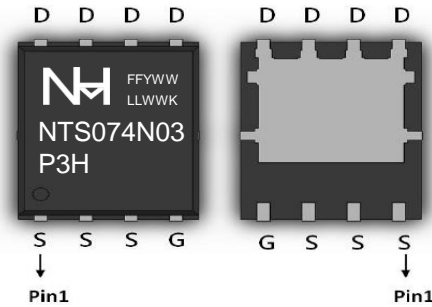
- Advanced trench MOSFET technology
- Low RDS(ON)
- Ultra Low Gate Charge
- RoHS Compliant
- 100% UIS and RG Tested
- High Power and current handing capability

**TYPICAL APPLICATIONS**

- PD Charger V-BUS
- SMPS 2nd Synchronous Rectifier
- MB/VGA Vcore
- BLDC Motor driver
- POL application

**PRODUCT SUMMARY**

$B_{V_{DS}}$ , Min. at Max. Tj	30	V
$I_D$	50	A
$R_{DS(ON)}$ , Max. at Vgs=10V	7.4	mΩ
Qg, Typ.	16	nC



Remark:

- NH=niuhang trademark;
- FF=Product line code, According to actual changes  
YWW=Data code, According to actual changes  
LLWWF=Internal code, According to actual changes
- NTS074N03P3H=Model.

**Absolute Maximum Ratings (Ratings at 25°C ambient temperature unless otherwise specified)**

Parameter	Test Conditions	Symbol	Ratings	Unit
Drain-Source Voltage		$V_{DS}$	30	V
Gate-Source Voltage		$V_{GS}$	±20	V
Continuous Drain Current (Note 1)	Ta=25°C	$I_D$	50	A
	Ta=100°C		32	
Drain Current-Pulsed	(Note 1)	$I_{DM}$	150	A
Maximum Power Dissipation	Ta=25°C	$P_D$	30	W
Power Dissipation Derating Factor above 25°C	Ta=100°C		12	
Derating Factor		$D_F$	0.24	W/°C
Junction Temperature		$T_J$	-55 to 150	°C
Storage temperature range		$T_{STD}$	-55 to 150	°C
Avalanche Current, Single pulse	L= 0.1 mH	$I_{AS}$	21	A
Single Pulse Avalanche Energy	L=0.1mH, IAS=21A, VDD=15V, RG=25Ω, Starting TJ =25°C	$E_{AS}$	22	mJ

**Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified)**

Parameter	Symbol	Max	Unit
Thermal Resistance Junction to Ambient	$R_{θJA}$	110	°C/W
Thermal Resistance Junction-Case	$R_{θJC}$	4.2	°C/W

- Notes:
- Repetitive Rating : Pulse width limited by maximum junction temperature
  - The value of  $R_{θJA}$  is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with TA =25° C.  
The value in any given application depends on the user's specific board design. This transistor is sensitive to electrostatic discharge and should be handled with care.

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Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified)						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=24V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>Static on Characteristics</b>						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.1	1.6	2.1	V
Drain-Source On Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=8A$	-	6.2	7.4	m $\Omega$
		$V_{GS}=4.5V, I_D=6A$	-	8.5	10.0	
Forward Transconductance	$g_{FS}$	$V_{DS}=5V, I_D=8A$	-	12	-	S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=15V, V_{GS}=0V, f=1.0MHz$	-	1000	-	pF
Output Capacitance	$C_{oss}$		-	150	-	pF
Reverse Transfer Capacitance	$C_{rss}$		-	120	-	pF
<b>Switching Parameters</b>						
Turn-On Delay Time	$t_{d(on)}$	$V_{DS}=20V, I_D=20A, V_{GS}=10V, R_G=1.6\Omega$	-	6	-	ns
Turn-On Rise Time	$t_r$		-	22	-	ns
Turn-Off Delay Time	$t_{d(off)}$		-	48	-	ns
Turn-Off Rise Time	$t_f$		-	20	-	ns
Gate Resistance	$R_g$	$V_{DS}=0V, V_{GS}=0V, f=1.0MHz$	-	3.50	-	$\Omega$
Total Gate Charge	$Q_g$	$V_{DS}=25V, I_D=8A, V_{GS}=10V$	-	30	-	nC
Gate-Source Charge	$Q_{gs}$		-	2	-	nC
Gate-Drain Charge	$Q_{gd}$		-	9.0	-	nc
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Max. Diode Forward Current	$I_{SD}$		-	-	50	A
Max. Pulsed Forward Current	$I_{SM}$		-	-	150	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=10A$	-	0.70	1.1	V
Reverse Recovery Time	$t_{rr}$	$I_F=8A, di/dt=100A/\mu s$	-	14	-	ns
Reverse Recovery Charge	$Q_{rr}$		-	6	-	$\mu C$

NTS074N03P3H

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Typical Characteristics Curves

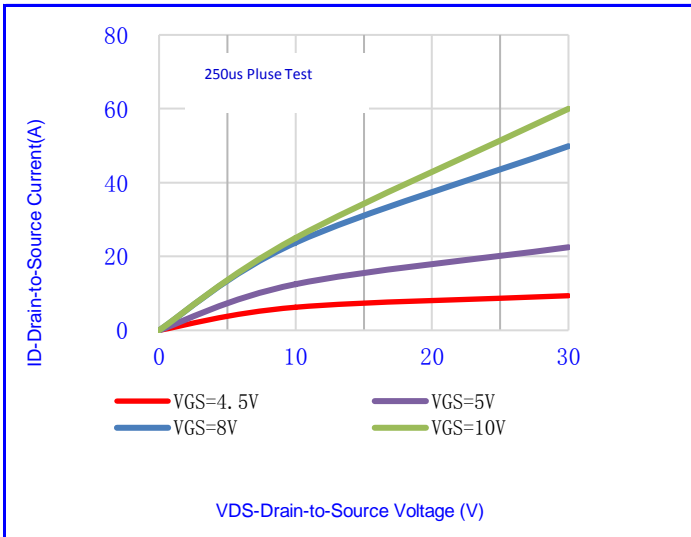


Fig.1-Output Characteristics

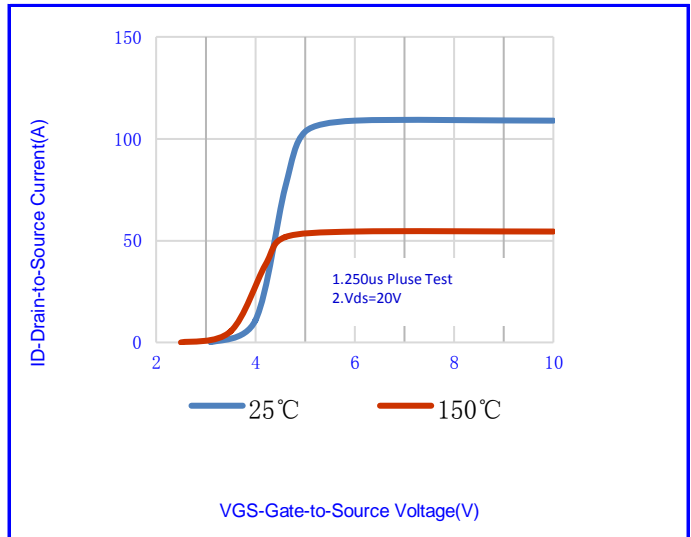


Fig.2- Transfer Characteristics

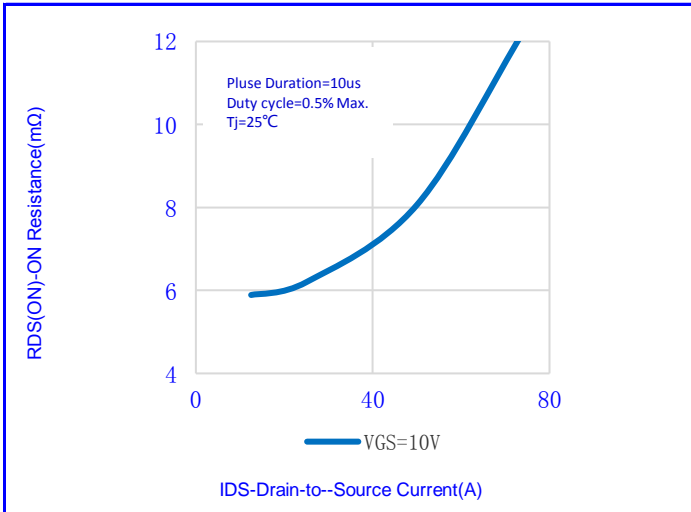


Fig.3- On Resistance vs. Drain Current

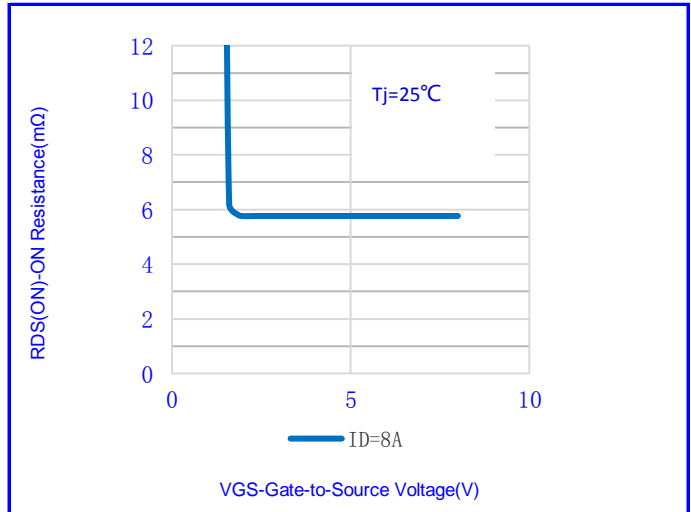


Fig.4- On Resistance vs. Gate Source Voltage

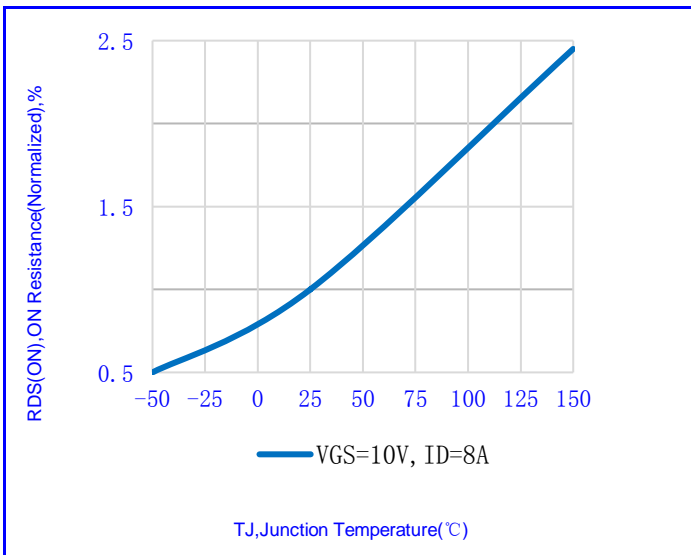


Fig.5- On Resistance vs. Junction Temperature

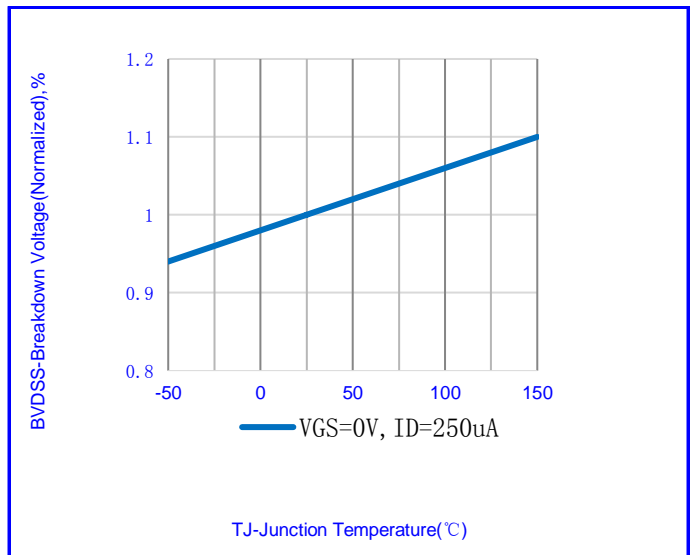


Fig.6- Breakdown Voltage vs. Junction Temperature

NTS074N03P3H

N-channel 30V Enhancement Mode Power MOSFET



Typical Characteristics Curves

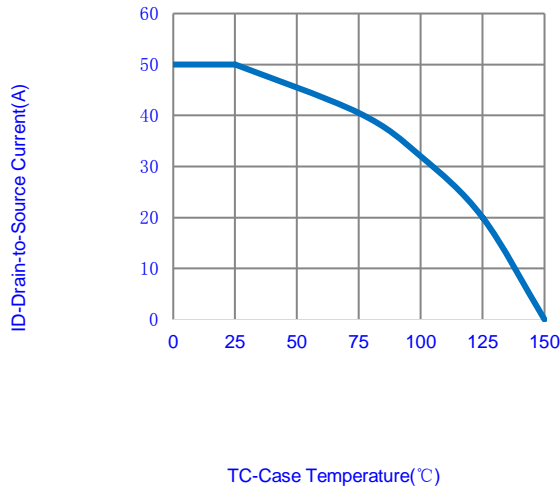


Fig.7-Maximum Continuous Drain Current vs. Case Temperature

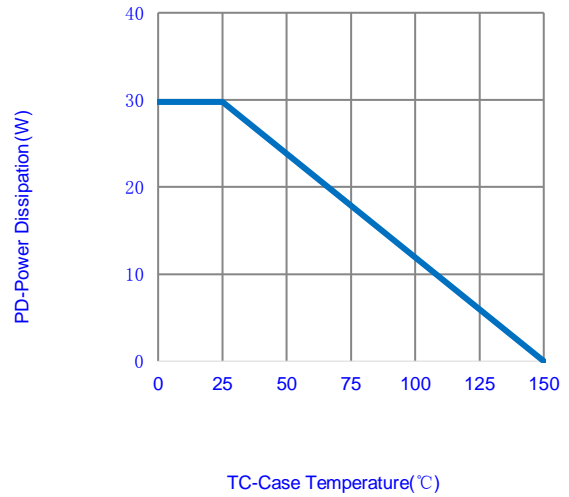


Fig.8-Maximum Power Dissipation vs. Case Temperature

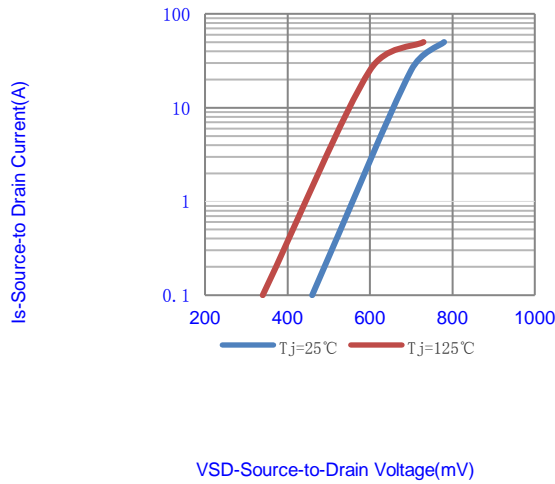


Fig.9- Source-Drain Diode Forward Voltage

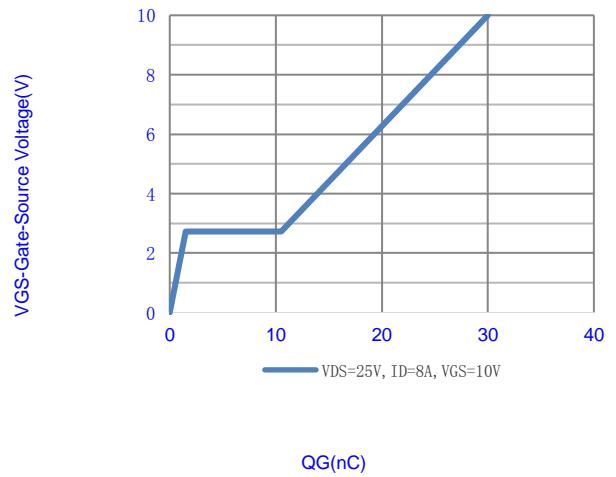


Fig.10-Gate Charge Waveform

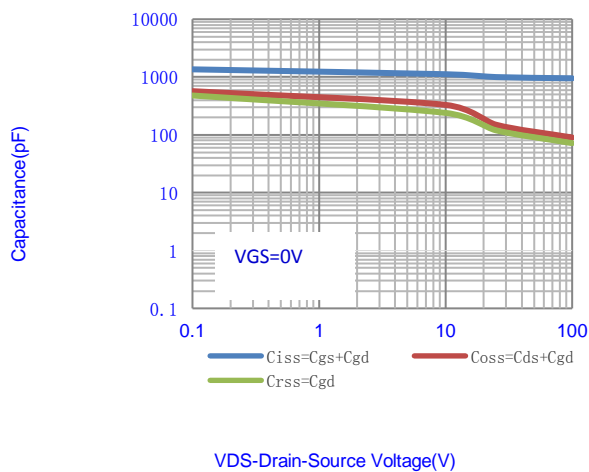


Fig.11- Gate-Source Voltage-VGS(V)

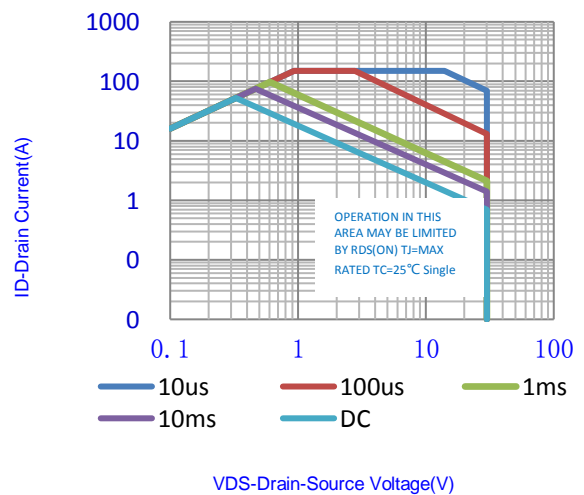


Fig.12-Maximum Safe Operating Area(SOA)

NTS074N03P3H

N-channel 30V Enhancement Mode Power MOSFET



Typical Characteristics Curves

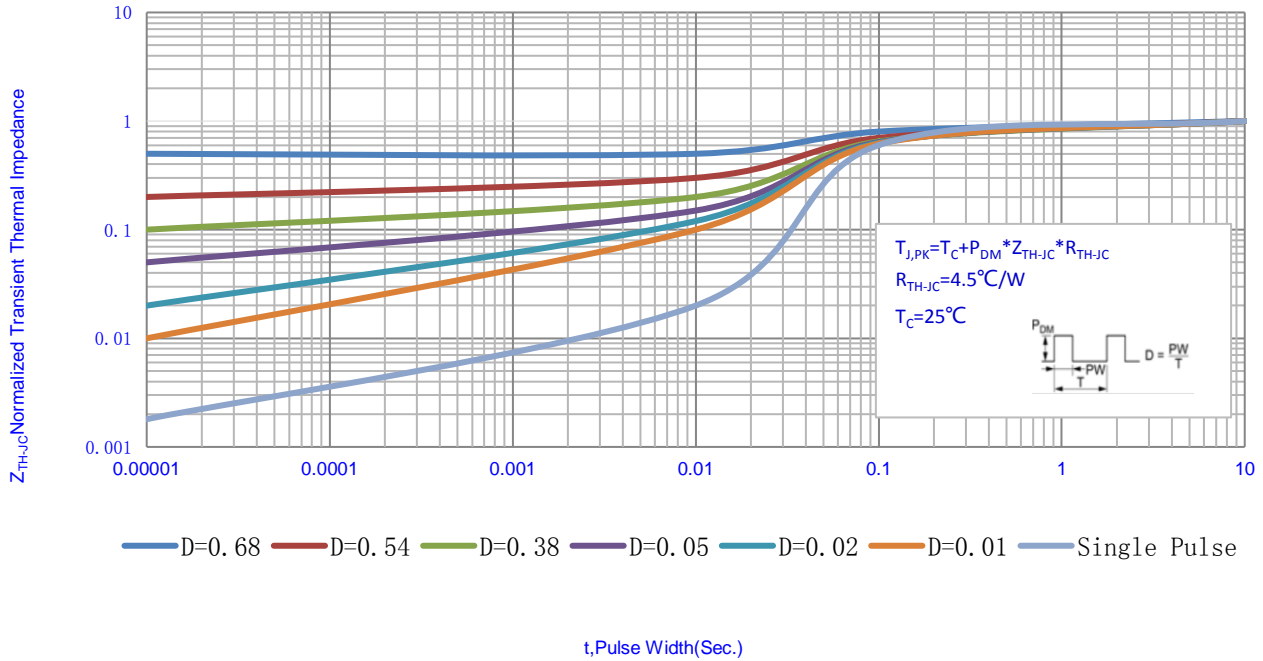


Fig.13- Normalized Transient Thermal Impedance vs. Pulse Width

NTS074N03P3H

N-channel 30V Enhancement Mode Power MOSFET



Test Circuit & Waveform

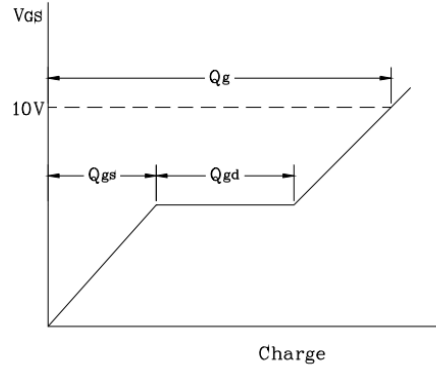
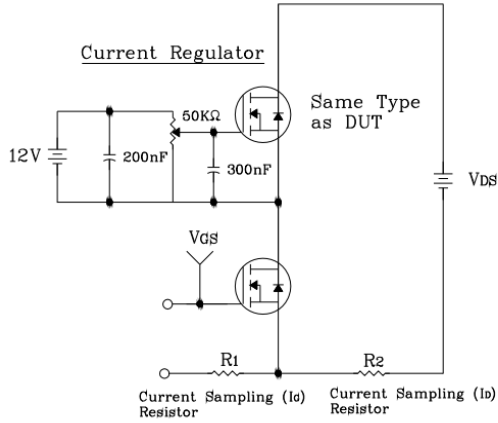


Fig.12-Gate Charge Test Circuit & Waveform

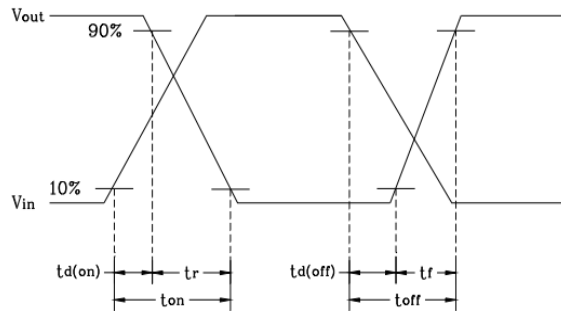
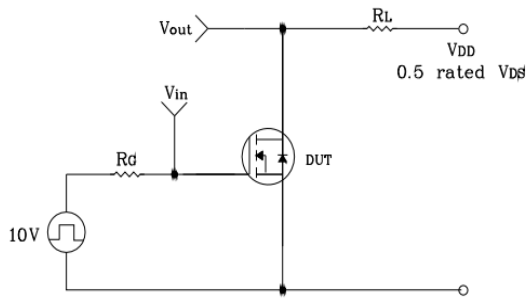


Fig.13- Resistive Switching Test Circuit & Waveform

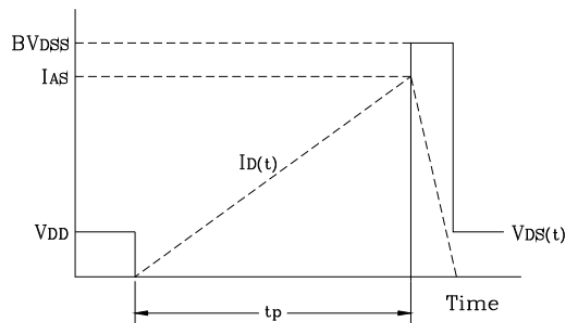
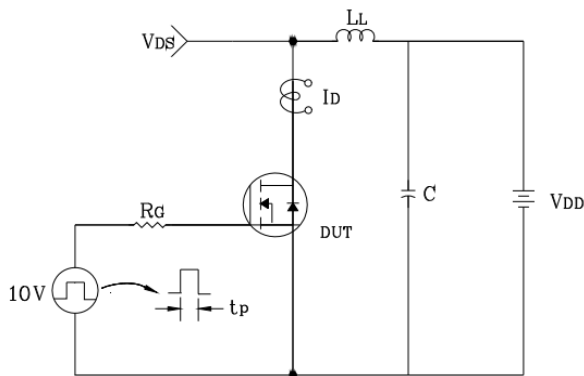


Fig.14- EAS Test Circuit & Waveform

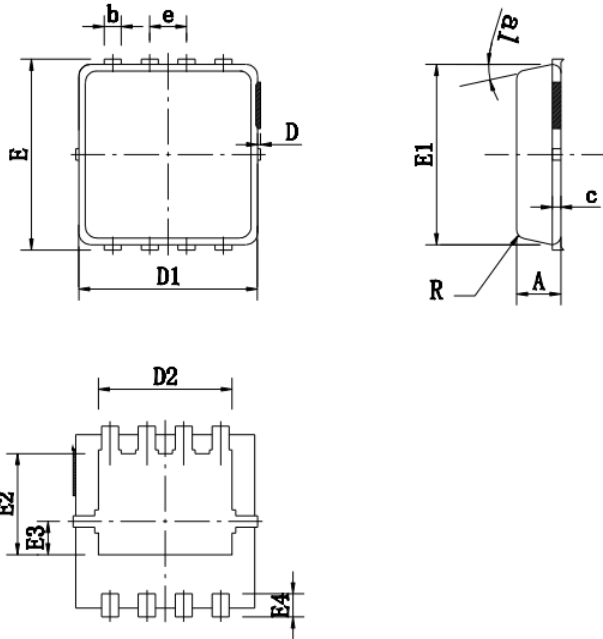
NTS074N03P3H

N-channel 30V Enhancement Mode Power MOSFET



OUTLINE DRAWINGS

PDFN3\*3



OUTLINE DIMENSIONS

Dim.	Milimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.750	0.780	0.810	0.030	0.031	0.032
b	0.297	0.300	0.350	0.012	0.012	0.014
c	-	0.152	-	-	0.006	-
D	0.000	0.050	0.100	0.000	0.002	0.004
D1	3.120	3.150	3.180	0.123	0.124	0.125
D2	-	2.350	-	-	0.093	-
E	3.200	3.300	3.400	0.126	0.130	0.134
E1	3.090	3.120	3.150	0.122	0.123	0.124
E2	-	1.750	-	-	0.069	-
E3	-	0.575	-	-	0.023	-
E4	-	0.400	-	-	0.016	-
R	-	0.150	-	-	0.006	-
e	-	0.650	-	-	0.026	-
a1	-	12°	-	-	12°	-

PACKING INFORMATION

PDFN3\*3

Package Method	Reel Size (mm)	Quantity (pcs/reel)	Inner Box Size LxWxH(mm)	Quantity (pcs/Inner Box)	Outer Carton Size LxWxH(mm)	Quantity (pcs/carton)
Tape Reel	Φ330	5000	340x340x50	10000	360x360x260	50000

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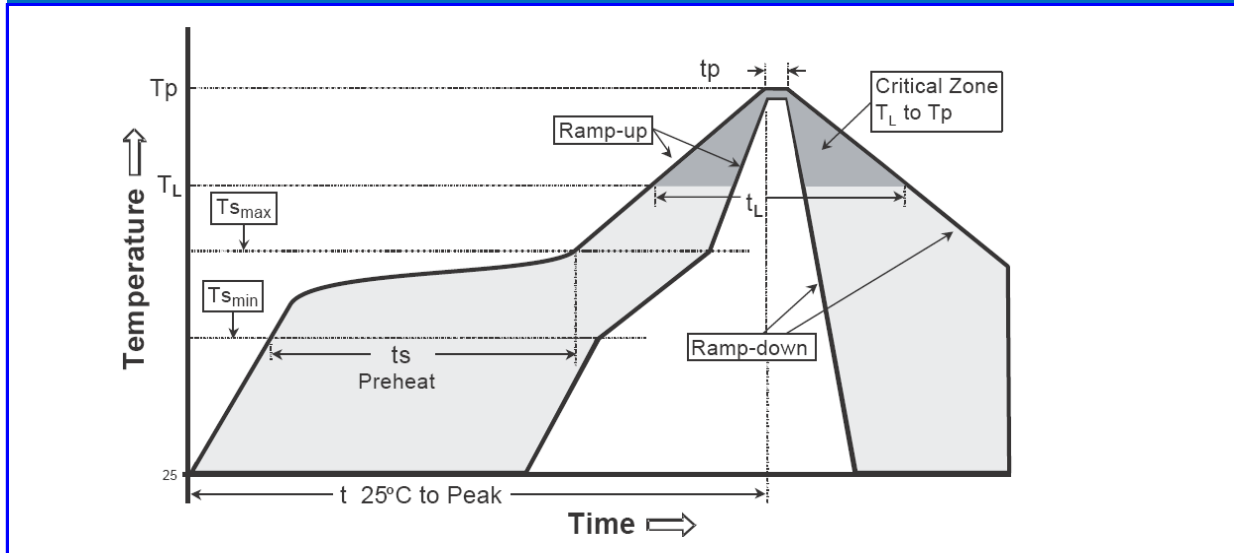
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**Recommended wave soldering condition**

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

**Recommended temperature profile for IR reflow**



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat -Temperature Min(TS min) -Temperature Max(TS max) -Time(ts min to ts max)	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: -Temperature (TL) - Time (tL)	183°C 60-150 seconds	217°C 60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.



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